

AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A light emitting device package, comprising:
 - a metal base;
 - an electrical circuit layer provided at an upper side of the metal base for providing a conductive path;
 - an insulating layer sandwiched between the metal base and the electrical circuit layer;
 - a light emitting device mounted on the top surface of the metal base in an open space from which the insulating layer is removed;
 - an electrode layer provided at an upper side of the electrical circuit layer;
 - a connection portion for electrically connecting the electrode layer and the light emitting device;
 - a silk screen layer formed on the top surface of the electrode layer; and
 - a lens portion attached to the silk screen layer.
2. (Original) The light emitting device package of claim 1, further comprising a molding portion for molding the inside of the open space.
3. – 5. (Canceled)
6. (Original) The light emitting device package of claim 1, wherein the open space is processed by milling.
7. (Original) The light emitting device package of claim 1, wherein the open space is processed by etching.
8. (Original) The light emitting device package of claim 1, wherein the light emitting device is one or more LED chips selected from the group consisting of a red LED chip, a green LED chip, a blue LED chip, a yellow LED chip and an orange LED chip.

9. (Original) The light emitting device package of claim 1, wherein the light emitting device comes in contact with the metal base.

10. (Canceled)

11. (Original) The light emitting device package of claim 1, wherein the light emitting device is combined to the metal base by a thermal conductive hardening agent.

12. (Original) The light emitting device package of claim 1, wherein the light emitting device is provided in a plurality of modules on one metal base, and the electrical circuit layer serially connects the respective modules.

13. (Original) The light emitting device package of claim 1, wherein the light emitting device is provided in a plurality of modules on one metal base, and the modules are arranged in either straight line, round or polygon.

14. (Original) The light emitting device package of claim 1, wherein a plating layer is provided on the top surface of the electrode layer.

15. – 26. (Canceled)

27. (Original) The light emitting device package of claim 1, wherein the lens portion is molded.

28. – 39. (Canceled)

40. (Previously Presented) A light emitting device package, comprising:
a metal base;

an electrical circuit layer provided at an upper side of the metal base for providing a conductive path;

an insulating layer sandwiched between the metal base and the electrical circuit layer;

a light emitting device mounted on the top surface of the metal base in an open space from which the insulating layer is removed;

an electrode layer provided at an upper side of the electrical circuit layer;

a connection portion for electrically connecting the electrode layer and the light emitting device; and

a heat sink on the bottom surface of the metal base,
wherein the heat sink is combined to the metal base by a screw.

41. (Currently Amended) The light emitting device package of claim 1, claim 40, further wherein the ~~comprising a heat sink that~~ comes in contact with one surface of the metal base with a heat transfer material embedded therein.

42. (Previously Presented) A light emitting device package, comprising:

a metal base;

an electrical circuit layer provided at an upper side of the metal base for providing a conductive path;

an insulating layer sandwiched between the metal base and the electrical circuit layer;

a light emitting device mounted on the top surface of the metal base in an open space from which the insulating layer is removed;

an electrode layer provided at an upper side of the electrical circuit layer;

a connection portion for electrically connecting the electrode layer and the light emitting device; and

a plating layer provided on the top surface of the electrode layer.

43. (Previously Presented) The light emitting device package of claim 42, wherein the plating layer is made of gold.

44. (Previously Presented) The light emitting device package of claim 42, wherein the electrode layer is plated at a thickness of 0.3mm or greater.

45. (Previously Presented) The light emitting device package of claim 42, wherein the electrical circuit layer and the electrode layer are formed at an overall thickness of the two layers within 200mm.

46. (Previously Presented) The light emitting device package of claim 42, wherein the electrode layer is formed by an electroplating method.

47. (Previously Presented) A light emitting device package, comprising:
a metal base;
an electrical circuit layer provided at an upper side of the metal base for providing a conductive path;
an insulating layer sandwiched between the metal base and the electrical circuit layer;
a light emitting device mounted on the top surface of the metal base in an open space from which the insulating layer is removed;
an electrode layer provided at an upper side of the electrical circuit layer; and
a connection portion for electrically connecting the electrode layer and the light emitting device;
wherein the light emitting device comprises one or more SiOB chips.